

Title (en)

ELECTROACOUSTIC TRANSDUCER AND METHOD OF MANUFACTURE THEREOF

Title (de)

ELEKTROAKUSTISCHER WANDLER UND DESSEN HERSTELLUNGSVERFAHREN

Title (fr)

TRANSDUCTEUR ELECTROACOUSTIQUE ET PROCEDE DE FABRICATION

Publication

EP 1164574 A4 20060719 (EN)

Application

EP 00971825 A 20001107

Priority

- JP 0007813 W 20001107
- JP 36025599 A 19991220

Abstract (en)

[origin: EP1164574A1] An electro-acoustic transducer having a layer of a heat-curing and UV-curing adhesive 6a formed on a frame 2 integrally molded at the bottom of a case 1. A magnet 5 is placed on the frame 2 via the adhesive. Said case 1 is irradiated with a UV light from the above, at least before the adhesive is heat-cured, so that the adhesive is cured in the portion exposed to the UV light. This prevents the adhesive 6a from evaporating, scattering and prevents the adhesive components depositing on a diaphragm 7, that could be caused by a later high temperature process for heat-curing the adhesive 6a. Furthermore, time for the heat-curing in the present invention can be made shorter by the high temperature curing. The shorter curing time improves productivity of the production, and enables to have the transducers manufactured on an automatic assembly line. <IMAGE>

IPC 1-7

G10K 9/13; H04R 13/00

IPC 8 full level

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Citation (search report)

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- [Y] WO 9834992 A1 19980813 - SIEMENS AG [DE], et al
- [A] GB 2119810 A 19831123 - GRACE W R & CO
- [A] PATENT ABSTRACTS OF JAPAN vol. 003, no. 067 (E - 116) 9 June 1979 (1979-06-09)
- See references of WO 0146943A1

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